SMALL-OUTLINE DRAM MODULE

MT4LDT464H (X)(S), MT8LDT864H (X)(S)

For the latest data sheet, please refer to the Micron Web site: www.micronsemi.com/datasheets/datasheet.html

FEATURES

- JEDEC pinout in a 144-pin, small-outline, dual in-line memory module (SODIMM)
- 32MB (4 Meg x 64) and 64MB (8 Meg x 64)
- High-performance CMOS silicon-gate process
- Single +3.3V ±0.3V power supply
- All inputs, outputs and clocks are TTL-compatible
- 4,096-cycle CAS#-BEFORE-RAS# (CBR) refresh distributed across 64ms
- FAST PAGE MODE (FPM) or Extended Data-Out (EDO) PAGE MODE access cycles
- Optional Self Refresh Mode (S)
- Serial presence-detect (SPD)

OPTIONS / MARKING

OPTIONS	MARKING
• Package	
144-pin SODIMM (gold)	G
• Timing	
50ns access	-5
60ns access	-6
• Access Cycles	
FAST PAGE MODE	None
EDO PAGE MODE	X
• Refresh Rates	
Standard Refresh	None
Self Refresh (128ms period)	S*

*Contact factory for availability

KEY TIMING PARAMETERS

FPM Operating Mode

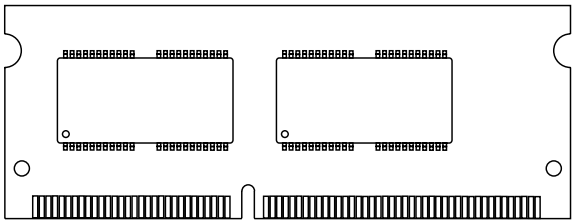
SPEED	tRC	tRAC	tPC	tAA	tCAC	tRP
-5	90ns	50ns	30ns	25ns	13ns	30ns
-6	110ns	60ns	35ns	30ns	15ns	40ns

EDO Operating Mode

SPEED	tRC	tRAC	tPC	tAA	tCAC	tCAS
-5	84ns	50ns	20ns	25ns	13ns	8ns
-6	104ns	60ns	25ns	30ns	15ns	10ns

PIN ASSIGNMENT (Front View)

144-Pin Small-Outline DIMM
(I-1; 32MB)
(I-2; 64MB)



PIN	FRONT	PIN	BACK	PIN	FRONT	PIN	BACK
1	VSS	2	VSS	73	OE#	74	RFU
3	DQ0	4	DQ32	75	VSS	76	VSS
5	DQ1	6	DQ33	77	RSVD	78	RSVD
7	DQ2	8	DQ34	79	RSVD	80	RSVD
9	DQ3	10	DQ35	81	VDD	82	VDD
11	VDD	12	VDD	83	DQ16	84	DQ48
13	DQ4	14	DQ36	85	DQ17	86	DQ49
15	DQ5	16	DQ37	87	DQ18	88	DQ50
17	DQ6	18	DQ38	89	DQ19	90	DQ51
19	DQ7	20	DQ39	91	VSS	92	VSS
21	VSS	22	VSS	93	DQ20	94	DQ52
23	CAS0#	24	CAS4#	95	DQ21	96	DQ53
25	CAS1#	26	CAS5#	97	DQ22	98	DQ54
27	VDD	28	VDD	99	DQ23	100	DQ55
29	A0	30	A3	101	VDD	102	VDD
31	A1	32	A4	103	A6	104	A7
33	A2	34	A5	105	A8	106	A11
35	VSS	36	VSS	107	VSS	108	VSS
37	DQ8	38	DQ40	109	A9	110	NC (A12)
39	DQ9	40	DQ41	111	A10	112	NC (A13)
41	DQ10	42	DQ42	113	VDD	114	VDD
43	DQ11	44	DQ43	115	CAS2#	116	CAS6#
45	VDD	46	VDD	117	CAS3#	118	CAS7#
47	DQ12	48	DQ44	119	VSS	120	VSS
49	DQ13	50	DQ45	121	DQ24	122	DQ56
51	DQ14	52	DQ46	123	DQ25	124	DQ57
53	DQ15	54	DQ47	125	DQ26	126	DQ58
55	VSS	56	VSS	127	DQ27	128	DQ59
57	RSVD	58	RSVD	129	VDD	130	VDD
59	RSVD	60	RSVD	131	DQ28	132	DQ60
61	RFU	62	RFU	133	DQ29	134	DQ61
63	VDD	64	VDD	135	DQ30	136	DQ62
65	RFU	66	RFU	137	DQ31	138	DQ63
67	WE#	68	RFU	139	VSS	140	VSS
69	RAS0#	70	NC	141	SDA	142	SCL
71	NC	72	NC	143	VDD	144	VDD

NOTE: Symbols in parentheses are not used on these modules but may be used for other modules in this product family. They are for reference only.

PART NUMBERS

FPM Operating Mode

PART NUMBER	CONFIGURATION	REFRESH
MT4LDT464HG-x	4 Meg x 64	Standard
MT4LDT464HG-xS	4 Meg x 64	Self
MT8LDT864HG-x	8 Meg x 64	Standard
MT8LDT864HG-xS	8 Meg x 64	Self

x = speed

EDO Operating Mode

PART NUMBER	CONFIGURATION	REFRESH
MT4LDT464HG-xX	4 Meg x 64	Standard
MT4LDT464HG-xXS	4 Meg x 64	Self
MT8LDT864HG-xX	8 Meg x 64	Standard
MT8LDT864HG-xXS	8 Meg x 64	Self

x = speed

GENERAL DESCRIPTION

The MT4LDT464H (X)(S) and MT8LDT864H (X)(S) are randomly accessed 32MB and 64MB memories organized in a small-outline, x64 configuration. They are specially processed to operate from 3V to 3.6V for low-voltage memory systems.

During READ or WRITE cycles, each location is uniquely addressed via the address bits. The row address is latched by the RAS# signal, then the column address is latched by the CAS# signal.

READ and WRITE cycles are selected with the WE# input. A logic HIGH on WE# dictates read mode, while a logic LOW on WE# dictates write mode. During a WRITE cycle, data-in (D) is latched by the falling edge of WE# or CAS#, whichever occurs last. An EARLY WRITE occurs when WE# is taken LOW prior to CAS# falling. A LATE WRITE or READ-MODIFY-WRITE occurs when WE# falls after CAS# is taken LOW. During EARLY WRITE cycles, the data outputs (Q) will remain High-Z, regardless of the state of OE#. During LATE WRITE or READ-MODIFY-WRITE cycles, OE# must be taken HIGH to disable the data outputs prior to applying input data. If a LATE WRITE or READ-MODIFY-WRITE is attempted while keeping OE# LOW, no WRITE will occur, and the data outputs will drive read data from the access location.

FAST PAGE MODE

FAST-PAGE-MODE operations allow faster data operations (READ or WRITE) within a row-address-defined page boundary. The FAST-PAGE-MODE cycle is always initiated with a row address strobed in by RAS#, followed by a column address strobed in by CAS#. Additional columns may be accessed by providing valid column addresses, strobing CAS# and holding RAS# LOW, thus executing faster memory cycles. Returning RAS# HIGH terminates the FAST-PAGE-MODE operation.

EDO PAGE MODE

EDO PAGE MODE, designated by the "X" option, is an accelerated FAST-PAGE-MODE cycle. The primary advantage of EDO is the availability of data-out even after CAS# goes back HIGH. EDO provides for CAS# precharge time (^{t}CP) to occur without the output data going invalid. This elimination of CAS# output control provides for pipelined READs.

FAST-PAGE-MODE modules have traditionally turned the output buffers off (High-Z) with the rising edge of CAS#. EDO operates as any DRAM READ or FAST-PAGE-MODE READ, except data will be held valid after CAS# goes HIGH, as long as RAS# and OE# are held LOW and WE# is held HIGH. (Refer to the 8 Meg x 8 EDO DRAM data sheet for additional information on EDO functionality.)

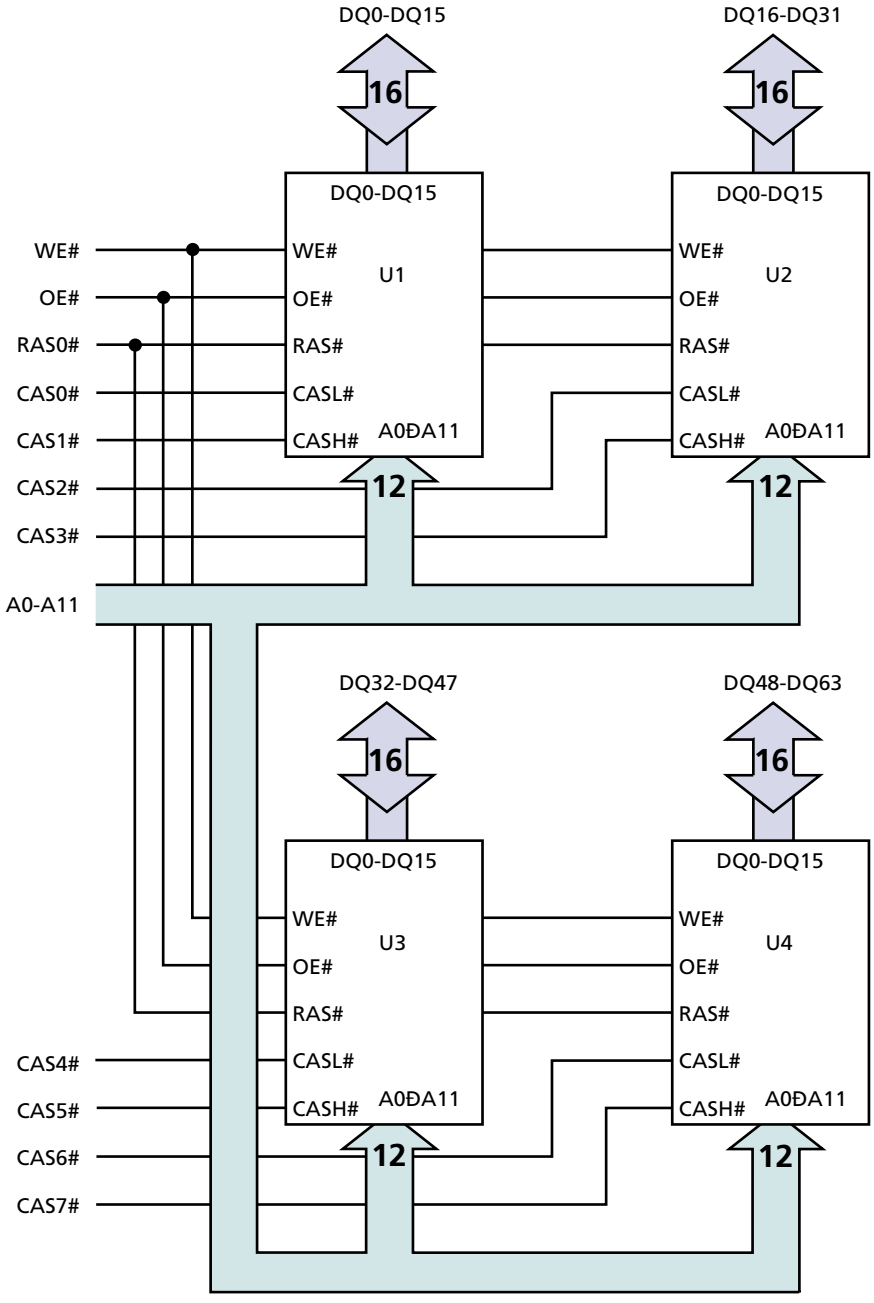
REFRESH

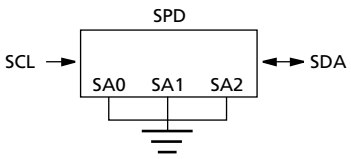
Memory cell data is retained in its correct state by maintaining power and executing any RAS# cycle (READ, WRITE) or RAS# refresh cycle (RAS#-ONLY, CBR or HIDDEN) so that all combinations of RAS# addresses are executed at least every ^{t}REF, regardless of sequence. The CBR REFRESH cycle will invoke the internal refresh counter for automatic RAS# addressing.

An optional self refresh mode is also available on the "S" version. The "S" option allows the user the choice of a fully static, low-power data retention mode or a dynamic refresh mode at the extended refresh period of 128ms, or 125µs per row when using distributed CBR REFESH. The optional self refresh feature is initiated by performing a CBR REFRESH cycle and holding RAS# LOW for the specified ^{t}RASS.

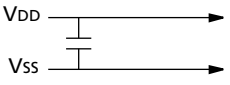
The self refresh mode is terminated by driving RAS# HIGH for a minimum time of ^{t}RPS. This delay allows for the completion of any internal refresh cycles that may be in process at the time of the RAS# LOW-to-HIGH transition. If the DRAM controller uses a distributed refresh sequence, a burst refresh is not required upon exiting self refresh. However, if the DRAM controller utilizes a RAS#-ONLY or burst refresh sequence, all 1,240 rows must be refreshed within the average internal refresh rate, prior to the resumption of normal operation.

FUNCTIONAL BLOCK DIAGRAM
MT4LDT464H (X) (32MB)

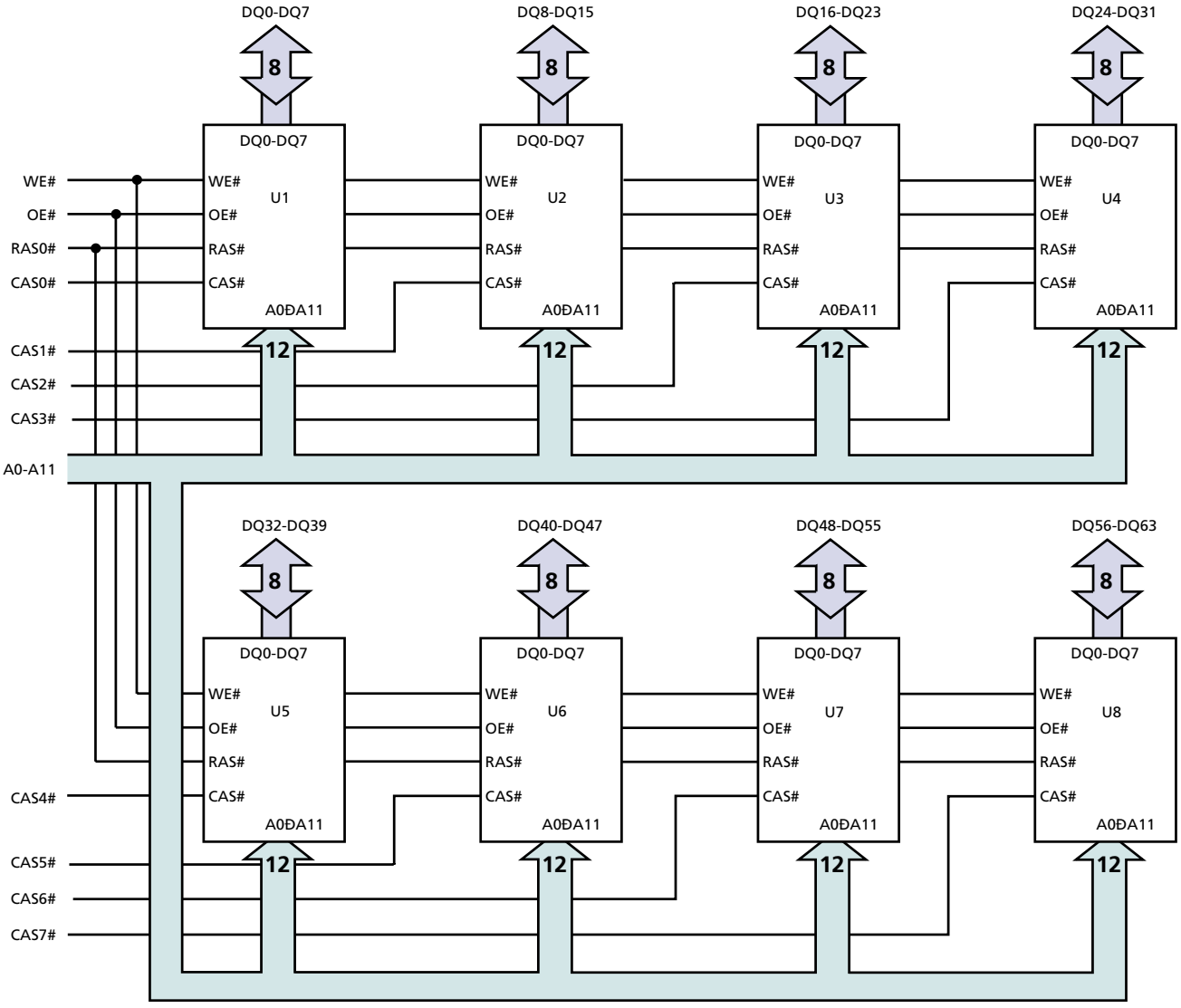


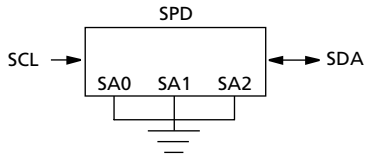


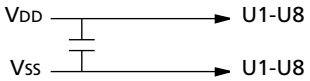
U1-U4 = MT4LC4M16R6 EDO PAGE MODE
U1-U4 = MT4LC4M16F5 FAST PAGE MODE



FUNCTIONAL BLOCK DIAGRAM
MT8LDT864H (X) (64MB)







U1-U8 = MT4LC8M8B6 FAST PAGE MODE

U1-U8 = MT4LC8M8C2 EDO PAGE MODE

STANDBY

Returning RAS# and CAS# HIGH terminates a memory cycle and decreases chip current to a reduced standby level. Also, the chip is preconditioned for the next cycle during the RAS# HIGH time.

SERIAL PRESENCE-DETECT OPERATION

This module family incorporates serial presence-detect (SPD). The SPD function is implemented using a 2,048-bit EEPROM. This nonvolatile storage device contains 256 bytes. The first 128 bytes can be programmed by Micron to identify the module type and various DRAM organizations and timing parameters. The remaining 128 bytes of storage are available for use by the customer. System READ/WRITE operations between the master (system logic) and the slave EEPROM device (DIMM) occur via a standard IIC bus using the DIMM's SCL (clock) and SDA (data) signals.

SPD CLOCK AND DATA CONVENTIONS

Data states on the SDA line can change only during SCL LOW. SDA state changes during SCL HIGH are reserved for indicating start and stop conditions (Figures 1 and 2).

SPD START CONDITION

All commands are preceded by the start condition, which is a HIGH-to-LOW transition of SDA when SCL is HIGH. The SPD device continuously monitors the SDA and SCL lines for the start condition and will not respond to any command until this condition has been met.

SPD STOP CONDITION

All communications are terminated by a stop condition, which is a LOW-to-HIGH transition of SDA when SCL is HIGH. The stop condition is also used to place the SPD device into standby power mode.

SPD ACKNOWLEDGE

Acknowledge is a software convention used to indicate successful data transfers. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle, the receiver will pull the SDA line LOW to acknowledge that it received the eight bits of data (Figure 3).

The SPD device will always respond with an acknowledge after recognition of a start condition and its slave address. If both the device and a WRITE

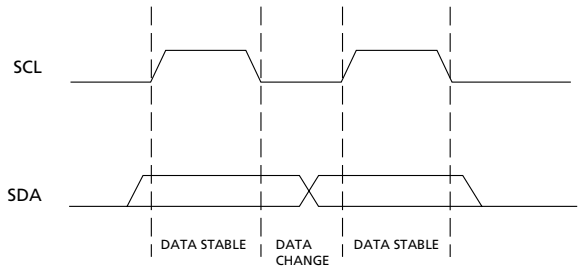


Figure 1
Data Validity

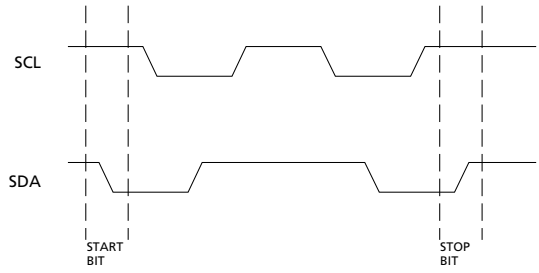


Figure 2
Definition of Start and Stop

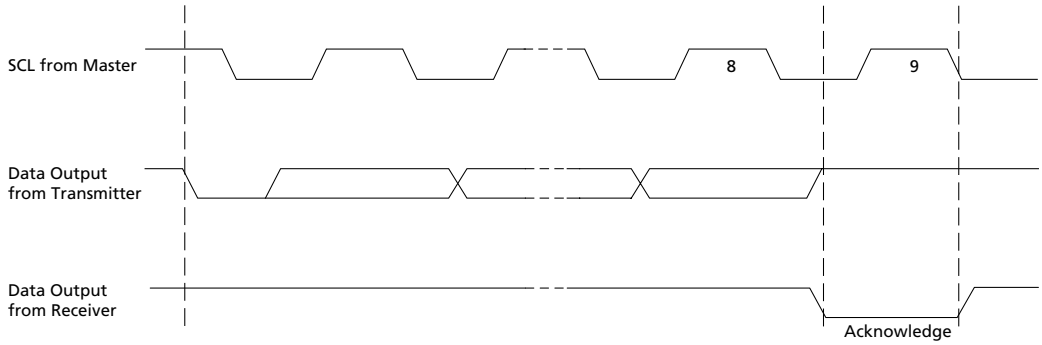


Figure 3
Acknowledge Response From Receiver

operation have been selected, the SPD device will respond with an acknowledge after the receipt of each subsequent eight-bit word. In the read mode the SPD device will transmit eight bits of data, release the SDA line and monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is generated by the master, the slave will continue to transmit data. If an acknowledge is not detected, the slave will terminate further data transmissions and await the stop condition to return to standby power mode.

SERIAL PRESENCE-DETECT MATRIX

BYTE	DESCRIPTION	ENTRY (VERSION)	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0	HEX
0	NUMBER OF BYTES USED BY MICRON	128	1	0	0	0	0	0	0	0	80
1	TOTAL NUMBER OF SPD MEMORY BYTES	256	0	0	0	0	1	0	0	0	08
2	MEMORY TYPE	FAST PAGE MODE	0	0	0	0	0	0	0	1	01
		EDO PAGE MODE	0	0	0	0	0	0	1	0	02
3	NUMBER OF ROW ADDRESSES	12	0	0	0	0	1	1	0	0	0C
4	NUMBER OF COLUMN ADDRESSES	10 (32MB)	0	0	0	0	1	0	1	0	0A
		11 (64MB)	0	0	0	0	1	0	1	1	0B
5	NUMBER OF BANKS	1	0	0	0	0	0	0	0	1	01
6	MODULE DATA WIDTH	64	0	1	0	0	0	0	0	0	40
7	MODULE DATA WIDTH (continued)	0	0	0	0	0	0	0	0	0	00
8	MODULE VOLTAGE INTERFACE LEVELS	LVTTL	0	0	0	0	0	0	0	1	01
9	RAS# ACCESS TIME (^{t}RAC)	50ns (-5)	0	0	1	1	0	0	1	0	32
		60ns (-6)	0	0	1	1	1	1	0	0	3C
10	CAS# ACCESS TIME (^{t}CAC)	13ns (-5)	0	0	0	0	1	1	0	1	0D
		15ns (-6)	0	0	0	0	1	1	1	1	0F
11	MODULE CONFIGURATION TYPE	NONPARITY	0	0	0	0	0	0	0	0	00
12	REFRESH RATE/TYPE 15.6µs/NORMAL	0	0	0	0	0	0	0	0	00	
		2x - 31.25µs/SELF	1	0	0	0	0	0	1	1	03
13	DRAM WIDTH (PRIMARY DRAM)	x16 (32MB)	0	0	0	1	0	0	0	0	10
		x8 (64MB)	0	0	0	0	1	0	0	0	08
14	ERROR CHECKING DRAM DATA WIDTH	NONE	0	0	0	0	0	0	0	0	00
15-61	RESERVED		0	0	0	0	0	0	0	0	00
62	SPD REVISION	REV. 0	0	0	0	0	0	0	0	0	00
63	CHECKSUM FOR BYTES 0-62	32MB -5 (EDO)	0	0	1	1	0	0	0	1	31
		32MB -6 (EDO)	0	0	1	1	1	1	0	1	3D
		32MB -5 (FPM)	0	0	1	1	0	0	0	0	30
		32MB -6 (FPM)	0	0	1	1	1	1	0	0	3C
		64MB -5 (EDO)	0	0	1	0	1	0	1	0	2A
		64MB -6 (EDO)	0	0	1	1	0	1	1	0	36
		64MB -5 (FPM)	0	0	1	0	1	0	0	1	29
		64MB -6 (FPM)	0	0	1	1	0	1	0	1	35
64	MANUFACTURER'S JEDEC ID CODE	MICRON	0	0	1	0	1	1	0	0	2C
65-71	MANUFACTURER'S JEDEC CODE (CONT.)		1	1	1	1	1	1	1	1	FF
72	MANUFACTURING LOCATION		0	0	0	0	0	0	0	1	01
			0	0	0	0	0	0	1	0	02
			0	0	0	0	0	0	1	1	03
			0	0	0	0	0	1	0	0	04
73-90	MODULE PART NUMBER (ASCII)		x	x	x	x	x	x	x	x	xx
91	PCB IDENTIFICATION CODE	1	0	0	0	0	0	0	0	1	01
		2	0	0	0	0	0	0	1	0	02
		3	0	0	0	0	0	0	1	1	03
		4	0	0	0	0	0	1	0	0	04
92	IDENTIFICATION CODE (CONT.)	0	0	0	0	0	0	0	0	0	00
93	YEAR OF MANUFACTURE IN BCD		x	x	x	x	x	x	x	x	xx
94	WEEK OF MANUFACTURE IN BCD		x	x	x	x	x	x	x	x	xx
95-98	MODULE SERIAL NUMBER		x	x	x	x	x	x	x	x	xx
99-125	MANUFACTURE SPECIFIC DATA (RSVD)		–	–	–	–	–	–	–	–	–

NOTE: 1. "1"/"0": Serial Data, "driven to HIGH"/"driven to LOW."
2. x = Variable Data.

ABSOLUTE MAXIMUM RATINGS*

Voltage on V_{DD} Supply
Relative to V_{SS} ..... -1V to +4.6V
Voltage on Inputs or I/O Pins
Relative to V_{SS} ..... -1V to +4.6V
Operating Temperature, T_A (ambient) .. 0°C to +70°C
Storage Temperature (plastic) ..... -55°C to +125°C
Power Dissipation (32MB) 4W
Power Dissipation (64MB) 8W

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND OPERATING CONDITIONS

(Notes: 1) (V_{DD} = +3.3V ±0.3V)

PARAMETER/CONDITION		SYMBOL	MIN	MAX	UNITS	NOTES
SUPPLY VOLTAGE		V_{DD}	3	3.6	V	
INPUT HIGH VOLTAGE: Logic 1; All inputs		V_{IH}	2	V_{DD} + 0.3	V	30
INPUT LOW VOLTAGE: Logic 0; All inputs		V_{IL}	-0.5	0.8	V	30
INPUT LEAKAGE CURRENT:	RAS0#	I_{I1}	-16	16	µA	23
Any input 0V ≤ V_{IN} ≤ V_{DD} + 0.3V	A0-A11, WE#, OE#	I_{I2}	-16	16	µA	23
(All other pins not under test = 0V)	CAS0#-CAS7#	I_{I3}	-2	2	µA	
OUTPUT LEAKAGE CURRENT: DQ is disabled; 0V ≤ V_{OUT} ≤ V_{DD} + 0.3V	DQ0-DQ63	I_{OZ}	-10	10	µA	
OUTPUT LEVELS: Output High Voltage (I_{OUT} = -2mA)		V_{OH}	2.4	–	V	
Output Low Voltage (I_{OUT} = 2mA)		V_{OL}	–	0.4	V	

I_{CC} OPERATING CONDITIONS AND MAXIMUM LIMITS

(Notes: 1, 5, 6) (V_{DD} = +3.3V ±0.3V)

PARAMETER/CONDITION	SYMBOL	SIZE	MAX -5	MAX -6	UNITS	NOTES
STANDBY CURRENT: TTL (RAS# = CAS# = V_{IH})	I_{CC1}	32MB 64MB	4 8	4 8	mA	
STANDBY CURRENT: CMOS (RAS# = CAS# = V_{DD} - 0.2V)	I_{CC2}	32MB 64MB	2 4	2 4	mA	26
OPERATING CURRENT: Random READ/WRITE Average power supply current (RAS#, CAS#, address cycling: ^{t}RC = ^{t}RC [MIN])	I_{CC3}	32MB 64MB	700 1400	660 1320	mA	3, 22
OPERATING CURRENT: FAST PAGE MODE Average power supply current (RAS# = V_{IL}, CAS#, address cycling: ^{t}PC = ^{t}PC [MIN]; ^{t}CP, ^{t}ASC = 10ns)	I_{CC4}	32MB 64MB	420 840	380 760	mA	3, 22
OPERATING CURRENT: EDO PAGE MODE Average power supply current (RAS# = V_{IL}, CAS#, address cycling: ^{t}PC = ^{t}PC [MIN])	I_{CC5} (X only)	32MB 64MB	620 1200	500 1000	mA	3, 22
REFRESH CURRENT: RAS#-ONLY Average power supply current (RAS# cycling, CAS# = V_{IH}: ^{t}RC = ^{t}RC [MIN])	I_{CC6}	32MB 64MB	700 1400	660 1320	mA	3, 22
REFRESH CURRENT: CBR Average power supply current (RAS#, CAS#, address cycling: ^{t}RC = ^{t}RC [MIN])	I_{CC7}	32MB 64MB	700 880	660 800	mA	3, 4
REFRESH CURRENT: Extended ("S" version only) Average power supply current: CAS# = 0.2V or CBR cycling; RAS# = ^{t}RAS (MIN); WE# = V_{DD} - 0.2V; A0-A11, OE# and D_{IN} = V_{DD} - 0.2V or 0.2V (D_{IN} may be left open)	I_{CC8}	32MB 64MB	1.6 3.2	1.6 3.2	mA	3, 4, 5
REFRESH CURRENT: Self ("S" version only) Average power supply current: CBR with RAS# ≥ $^{t}RASS$ (MIN) and CAS# held LOW; WE# = V_{DD} - 0.2V; A0-A11, OE# and D_{IN} = V_{DD} - 0.2V or 0.2V (D_{IN} may be left open)	I_{CC9}	32MB 64MB	1.6 2.4	1.6 2.4	mA	3, 4, 5

CAPACITANCE

PARAMETER	SYMBOL	MAX 32MB	MAX 64MB	UNITS	NOTES
Input Capacitance: A0-A11	C_{I1}	24	46	pF	2
Input Capacitance: WE#, OE#, RAS0#	C_{I2}	32	62	pF	2
Input Capacitance: CAS0#-CAS7#, SCL	C_{I3}	10	10	pF	2
Input/Output Capacitance: DQ0-DQ63	C_{IO1}	10	18	pF	2
Input/Output Capacitance: SDA	C_{IO2}	10	10	pF	2

FAST PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - FAST PAGE MODE OPTION		-5		-6			
PARAMETER	SYMBOL	MIIN	MAX	MIN	MAX	UNITS	NOTES
Access time from column address	^tAA		25		30	ns	
Column-address hold time (referenced to RAS#)	^tAR	40		45		ns	
Column-address setup time	^tASC	0		0		ns	
Row-address setup time	^tASR	0		0		ns	
Column address to WE# delay time	^tAWD	48		55		ns	27
Access time from CAS#	^tCAC		13		15	ns	
Column-address hold time	^tCAH	8		10		ns	
CAS# pulse width	^tCAS	13	10,000	15	10,000	ns	
CAS# LOW to "Don't Care" during Self Refresh	^tCHD	15		15		ns	27
CAS# hold time (CBR Refresh)	^tCHR	15		15		ns	4
CAS# to output in Low-Z	^tCLZ	3		3		ns	21
CAS# precharge time	^tCP	8		10		ns	13
Access time from CAS# precharge	^tCPA		30		35	ns	
CAS# to RAS# precharge time	^tCRP	5		5		ns	
CAS# hold time	^tCSH	50		60		ns	
CAS# setup time (CBR Refresh)	^tCSR	5		5		ns	
CAS# to WE# delay time	^tCWD	36		40		ns	27
WRITE command to CAS# lead time	^tCWL	13		15		ns	
Data-in hold time	^tDH	8		10		ns	18
Data-in setup time	^tDS	0		0		ns	18
Output disable	^tOD	3	13	3	15	ns	
Output enable	^tOE		13		15	ns	
OE# hold time from WE# during READ-MODIFY-WRITE cycle	^tOEH	13		15		ns	28
Output buffer turn-off delay	^tOFF	3	13	3	15	ns	17, 24
OE# setup prior to RAS# during HIDDEN REFRESH cycle	^tORD	0		0		ns	
FAST-PAGE-MODE READ or WRITE cycle time	^tPC	30		35		ns	
FAST-PAGE-MODE READ-WRITE cycle time	^tPRWC	76		85		ns	
Access time from RAS#	^tRAC		50		60	ns	
RAS# to column-address delay time	^tRAD	13		15		ns	15
Row-address hold time	^tRAH	8		10		ns	
RAS# pulse width	^tRAS	50	10,000	60	10,000	ns	
RAS# pulse width (FAST PAGE MODE)	^tRASP	50	125,000	60	125,000	ns	
RAS# pulse width during Self Refresh	^tRASS	100		100		µs	

FAST PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - FAST PAGE MODE OPTION		-5		-6			
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	UNITS	NOTES
Random READ or WRITE cycle time	^{t}RC	90		110		ns	
RAS# to CAS# delay time	^{t}RCD	18		20		ns	14
READ command hold time (referenced to CAS#)	^{t}RCH	0		0		ns	16
READ command setup time	^{t}RCS	0		0		ns	
Refresh period (4,096 cycles)	^{t}REF		64		64	ms	
RAS# precharge time	^{t}RP	30		40		ns	
RAS# to CAS# precharge time	^{t}RPC	0		0		ns	
RAS# precharge time exiting Self Refresh	^{t}RPS	90		105		ns	
READ command hold time (referenced to RAS#)	^{t}RRH	0		0		ns	16
RAS# hold time	^{t}RSH	13		15		ns	
READ-WRITE cycle time	^{t}RWC	131		155		ns	
RAS# to WE# delay time	^{t}RWD	73		85		ns	27
WRITE command to RAS# lead time	^{t}RWL	13		15		ns	
Transition time (rise or fall)	^{t}T	2	50	2	50	ns	
WRITE command hold time	^{t}WCH	8		10		ns	
WRITE command hold time (referenced to RAS#)	^{t}WCR	40		45		ns	
WE# command setup time	^{t}WCS	0		0		ns	27
WRITE command pulse width	^{t}WP	8		10		ns	
WE# hold time (CBR Refresh)	^{t}WRH	10		10		ns	
WE# setup time (CBR Refresh)	^{t}WRP	10		10		ns	

EDO PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - EDO PAGE MODE OPTION		-5		-6			
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	UNITS	NOTES
Access time from column address	^tAA		25		30	ns	
Column-address setup to CAS# precharge	^tACH	12		15		ns	
Column-address hold time (referenced to RAS#)	^tAR	38		45		ns	
Column-address setup time	^tASC	0		0		ns	
Row-address setup time	^tASR	0		0		ns	
Column address to WE# delay time	^tAWD	42		49		ns	27
Access time from CAS#	^tCAC		13		15	ns	
Column-address hold time	^tCAH	8		10		ns	
CAS# pulse width	^tCAS	8	10,000	10	10,000	ns	
CAS# LOW to "Don't Care" during Self Refresh	^tCHD	15		15		ns	
CAS# hold time (CBR Refresh)	^tCHR	8		10		ns	4
CAS# to output in Low-Z	^tCLZ	0		0		ns	
Data output hold after next CAS# LOW	^tCOH	3		3		ns	
CAS# precharge time	^tCP	8		10		ns	13
Access time from CAS# precharge	^tCPA		28		35	ns	
CAS# to RAS# precharge time	^tCRP	5		5		ns	
CAS# hold time	^tCSH	38		45		ns	
CAS# setup time (CBR Refresh)	^tCSR	5		5		ns	
CAS# to WE# delay time	^tCWD	28		35		ns	27
WRITE command to CAS# lead time	^tCWL	8		10		ns	
Data-in hold time	^tDH	8		10		ns	18
Data-in setup time	^tDS	0		0		ns	18
Output disable	^tOD	0	12	0	15	ns	
Output enable	^tOE		12		15	ns	
OE# hold time from WE# during READ-MODIFY-WRITE cycle	^tOEH	8		10		ns	28
OE# HIGH hold from CAS# HIGH	^tOEHC	5		10		ns	28
OE# HIGH pulse width	^tOEP	5		5		ns	
OE# LOW to CAS# HIGH setup time	^tOES	4		5		ns	
Output buffer turn-off delay	^tOFF	0	12	0	15	ns	17, 24

EDO PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - EDO PAGE MODE OPTION		-5		-6			
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	UNITS	NOTES
OE# setup prior to RAS# during HIDDEN REFRESH cycle	^{t}ORD	0		0		ns	
EDO-PAGE-MODE READ or WRITE cycle time	^{t}PC	20		25		ns	
EDO-PAGE-MODE READ-WRITE cycle time	^{t}PRWC	47		56		ns	
Access time from RAS#	^{t}RAC		50		60	ns	
RAS# to column-address delay time	^{t}RAD	9		12		ns	15
Row-address hold time	^{t}RAH	9		10		ns	
RAS# pulse width	^{t}RAS	50	10,000	60	10,000	ns	
RAS# pulse width (EDO PAGE MODE)	^{t}RASP	50	125,000	60	125,000	ns	
RAS# pulse width during Self Refresh	^{t}RASS	100		100		µs	
Random READ or WRITE cycle time	^{t}RC	84		104		ns	
RAS# to CAS# delay time	^{t}RCD	11		14		ns	14
READ command hold time (referenced to CAS#)	^{t}RCH	0		0		ns	16
READ command setup time	^{t}RCS	0		0		ns	
Refresh period (4,096 cycles)	^{t}REF		64		64	ms	
RAS# precharge time	^{t}RP	30		40		ns	
RAS# to CAS# precharge time	^{t}RPC	5		5		ns	
RAS# precharge time exiting Self Refresh	^{t}RPS	90		105		ns	
READ command hold time (referenced to RAS#)	^{t}RRH	0		0		ns	16
RAS# hold time	^{t}RSH	13		15		ns	
READ-WRITE cycle time	^{t}RWC	116		140		ns	
RAS# to WE# delay time	^{t}RWD	67		79		ns	28
WRITE command to RAS# lead time	^{t}RWL	13		15		ns	
Transition time (rise or fall)	^{t}T	2	50	2	50	ns	
WRITE command hold time	^{t}WCH	8		10		ns	
WRITE command hold time (referenced to RAS#)	^{t}WCR	38		45		ns	
WE# command setup time	^{t}WCS	0		0		ns	28
Output disable delay from WE#	^{t}WHZ	0	12	0	15	ns	
WRITE command pulse width	^{t}WP	5		5		ns	
WE# pulse to disable at CAS# HIGH	^{t}WPZ	10		10		ns	
WE# hold time (CBR Refresh)	^{t}WRH	8		10		ns	
WE# setup time (CBR Refresh)	^{t}WRP	8		10		ns	

SERIAL PRESENCE-DETECT EEPROM DC OPERATING CONDITIONS

(Notes: 1) (V_{DD} = +3.3V ±0.3V)

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
SUPPLY VOLTAGE	V_{DD}	3	3.6	V	
INPUT HIGH VOLTAGE: Logic 1; All inputs	V_{IH}	V_{DD} x 0.7	V_{DD} + 0.5	V	
INPUT LOW VOLTAGE: Logic 0; All inputs	V_{IL}	-1	V_{DD} x 0.3	V	
OUTPUT LOW VOLTAGE: I_{OUT} = 3mA	V_{OL}	–	0.4	V	
INPUT LEAKAGE CURRENT: V_{IN} = GND to V_{DD}	I_{LI}	–	10	µA	
OUTPUT LEAKAGE CURRENT: V_{OUT} = GND to V_{DD}	I_{LO}	–	10	µA	
STANDBY CURRENT: SCL = SDA = V_{DD} - 0.3V; All other inputs = GND or 3.3V +10%	I_{SB}	–	30	µA	
POWER SUPPLY CURRENT: SCL clock frequency = 100 KHz	I_{CC}	–	2	mA	

SERIAL PRESENCE-DETECT EEPROM AC ELECTRICAL CHARACTERISTICS

(Notes: 1) (V_{DD} = +3.3V ±0.3V)

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
SCL LOW to SDA data-out valid	^{t}AA	0.3	3.5	µs	
Time the bus must be free before a new transition can start	^{t}BUF	4.7		µs	
Data-out hold time	^{t}DH	300		ns	
SDA and SCL fall time	^{t}F		300	ns	
Data-in hold time	$^{t}HD:DAT$	0		µs	
Start condition hold time	$^{t}HD:STA$	4		µs	
Clock HIGH period	$^{t}HIGH$	4		µs	
Noise suppression time constant at SCL, SDA inputs	^{t}I		100	ns	
Clock LOW period	^{t}LOW	4.7		µs	
SDA and SCL rise time	^{t}R		1	µs	
SCL clock frequency	^{t}SCL		100	KHz	
Data-in setup time	$^{t}SU:DAT$	250		ns	
Start condition setup time	$^{t}SU:STA$	4.7		µs	
Stop condition setup time	$^{t}SU:STO$	4.7		µs	
WRITE cycle time	^{t}WR		10	ms	29

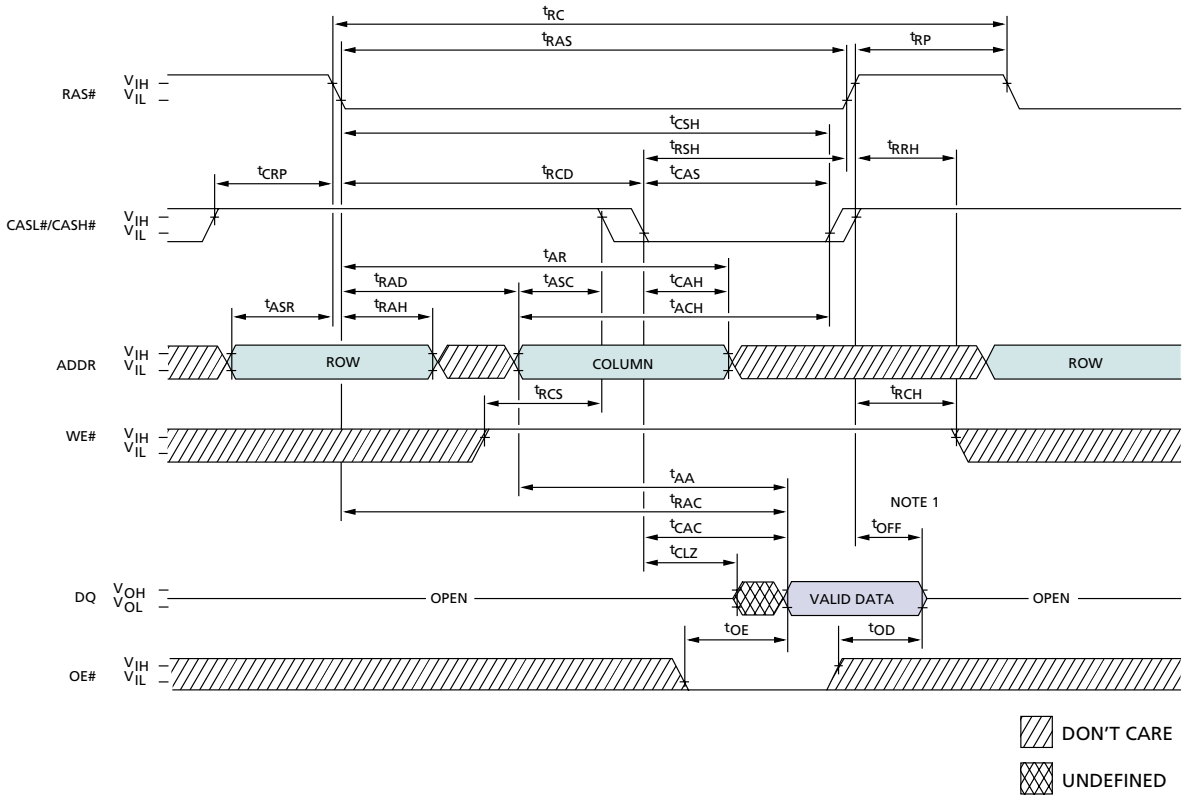
NOTES

1. All voltages referenced to V_{SS}.
2. This parameter is sampled. V_{DD} = +3.3V; f = 1 MHz.
3. I_{CC} is dependent on output loading and cycle rates. Specified values are obtained with minimum cycle time and the outputs open.
4. Enables on-chip refresh and address counters.
5. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range is ensured.
6. An initial pause of 100µs is required after power-up, followed by eight RAS# REFRESH cycles (RAS#-ONLY or CBR with WE# HIGH), before proper device operation is ensured. The eight RAS# cycle wake-ups should be repeated any time the ^{t}REF refresh requirement is exceeded.
7. AC characteristics assume ^{t}T = 5ns for FPM and ^{t}T = 2.5ns for EDO.
8. V_{IH} (MIN) and V_{IL} (MAX) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}).
9. In addition to meeting the transition rate specification, all input signals must transit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
10. If CAS# = V_{IH}, data output is High-Z.
11. If CAS# = V_{IL}, data output may contain data from the last valid READ cycle.
12. Measured with a load equivalent to two TTL gates and 100pF and V_{OL} = 0.8V and V_{OH} = 2V.
13. If CAS# is LOW at the falling edge of RAS#, Q will be maintained from the previous cycle. To initiate a new cycle and clear the data-out buffer, CAS# must be pulsed HIGH for ^{t}CP.
14. The ^{t}RCD (MAX) limit is no longer specified. ^{t}RCD (MAX) was specified as a reference point only. If ^{t}RCD was greater than the specified ^{t}RCD (MAX) limit, then access time was controlled exclusively by ^{t}CAC (^{t}RAC [MIN] no longer applied). With or without the ^{t}RCD (MAX) limit, ^{t}AA and ^{t}CAC must always be met.
15. The ^{t}RAD (MAX) limit is no longer specified. ^{t}RAD (MAX) was specified as a reference point only. If ^{t}RAD was greater than the specified ^{t}RAD (MAX) limit, then access time was controlled exclusively by ^{t}AA (^{t}RAC and ^{t}CAC no longer applied). With or without the ^{t}RAD (MAX) limit, ^{t}AA, ^{t}RAC and ^{t}CAC must always be met.
16. Either ^{t}RCH or ^{t}RRH must be satisfied for a READ cycle.
17. ^{t}OFF (MAX) defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL}.
18. These parameters are referenced to CAS# leading edge in EARLY WRITE cycles and WE# leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
19. If OE# is tied permanently LOW, LATE WRITE or READ-MODIFY-WRITE operations are not permissible and should not be attempted. Additionally, with EDO, WE# must be pulsed during CAS# HIGH time in order to place I/O buffers in High-Z.
20. A HIDDEN REFRESH may also be performed after a WRITE cycle. In this case, WE# = LOW and OE# = HIGH.
21. The 3ns minimum is a parameter guaranteed by design.
22. Column address changed once each cycle.
23. 8MB module values will be half of those shown.
24. With the FPM option, ^{t}OFF is determined by the first RAS# or CAS# signal to transition HIGH. In comparison, ^{t}OFF on an EDO option is determined by the latter of the RAS# and CAS# signals to transition HIGH.
25. Applies to both FPM and EDO operating modes.
26. All other inputs at 0.2V or V_{DD} - 0.2V.
27. ^{t}WCS, ^{t}RWD, ^{t}AWD and ^{t}CWD are not restrictive operating parameters. ^{t}WCS applies to EARLY WRITE cycles. ^{t}RWD, ^{t}AWD and ^{t}CWD apply to READ-MODIFY-WRITE cycles. If ^{t}WCS $\geq$ ^{t}WCS (MIN), the cycle is an EARLY WRITE cycle and the data output will remain an open circuit throughout the entire cycle. If ^{t}WCS < ^{t}WCS (MIN) and ^{t}RWD $\geq$ ^{t}RWD (MIN), ^{t}AWD $\geq$ ^{t}AWD (MIN) and ^{t}CWD $\geq$ ^{t}CWD (MIN), the cycle is a READ-MODIFY-WRITE and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of data-out is indeterminate. OE# held HIGH and WE# taken LOW after CAS# goes LOW result in a LATE WRITE (OE#-controlled) cycle. ^{t}WCS, ^{t}RWD, ^{t}CWD and ^{t}AWD are not applicable in a LATE WRITE cycle.

NOTES (continued)

28. LATE WRITE and READ-MODIFY-WRITE cycles must have both ^{t}OD and ^{t}OEH met (OE# HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The DQs will provide the previously read data if CAS# remains LOW and OE# is taken back LOW after ^{t}OEH is met. If CAS# goes HIGH prior to OE# going back LOW, the DQs will remain open.
29. The SPD EEPROM WRITE cycle time (^{t}WR) is the time from a valid stop condition of a write sequence to the end of the EEPROM internal erase/program cycle. During the WRITE cycle, the EEPROM bus interface circuit is disabled, SDA remains HIGH due to pull-up resistor, and the EEPROM does not respond to its slave address.
30. V_{IH} overshoot: V_{IH} (MAX) = V_{DD} + 2V for a pulse width ≤ 10ns, and the pulse width cannot be greater than one third of the cycle rate. V_{IL} undershoot: V_{IL} (MIN) = -2V for a pulse width ≤ 10ns, and the pulse width cannot be greater than one third of the cycle rate.

READ CYCLE [25]



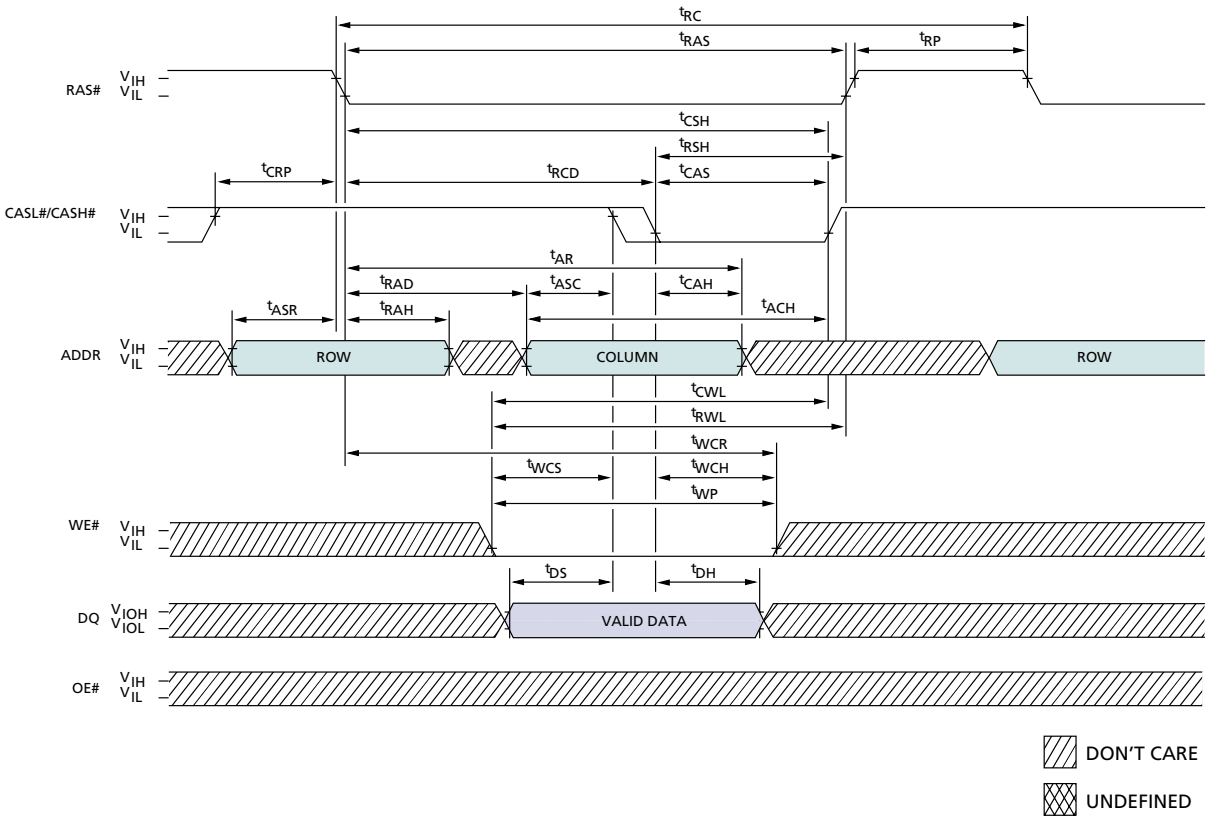
FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH (EDO)	12		15		ns
tAR (EDO)	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tAR (FPM)	40		45		ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	13	10,000	15	10,000	ns
tCLZ (EDO)	0		0		ns
tCLZ (FPM)	3		3		ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	50		60		ns
tOD (EDO)	0	12	0	15	ns
tOD (FPM)	3	13	3	15	ns
tOE (EDO)		12		15	ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOE (FPM)		13		15	ns
tOFF (EDO)	0	12	0	15	ns
tOFF (FPM)	3	13	3	15	ns
tRAC		50		60	ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	13		15		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (EDO)	84		104		ns
tRC (FPM)	90		110		ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	18		20		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRRH	0		0		ns
tRSH	13		15		ns

NOTE: 1. For EDO, tOFF is referenced from rising edge of RAS# or CAS#, whichever occurs last. For FPM, tOFF is referenced from rising edge of RAS# or CAS#, whichever occurs first.

EARLY WRITE CYCLE [25]

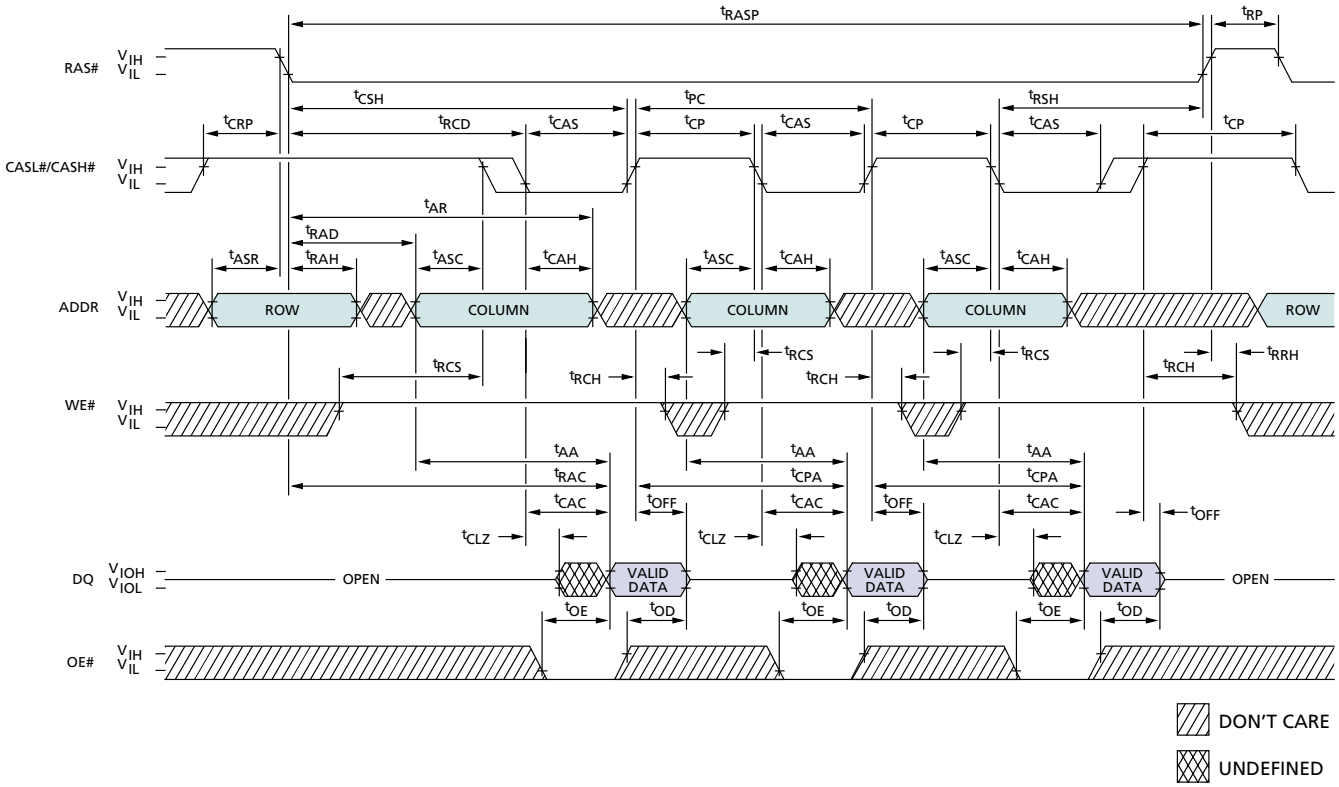


FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tACH (EDO)	12		15		ns
tAR (EDO)	38		45		ns
tAR (FPM)	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAH	8		10		ns
tCAS (FPM)	13	10,000	15	10,000	ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCRP	5		5		ns
tCSH (FPM)	50		60		ns
tCSH (EDO)	38		45		ns
tCWL (FPM)	13		15		ns
tCWL (EDO)	8		10		ns
tDH	8		10		ns
tDS	0		0		ns
tRAD (FPM)	—		15		ns
tRAD (EDO)	9		12		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (FPM)	90		110		ns
tRC (EDO)	84		104		ns
tRCD (FPM)	18		20		ns
tRCD (EDO)	11		14		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWL	13		15		ns
tWCH	8		10		ns
tWCR (EDO)	38		45		ns
tWCR (FPM)	40		45		ns
tWCS	0		0		ns
tWP (FPM)	8		10		ns
tWP (EDO)	5		5		ns

FAST-PAGE-MODE READ CYCLE

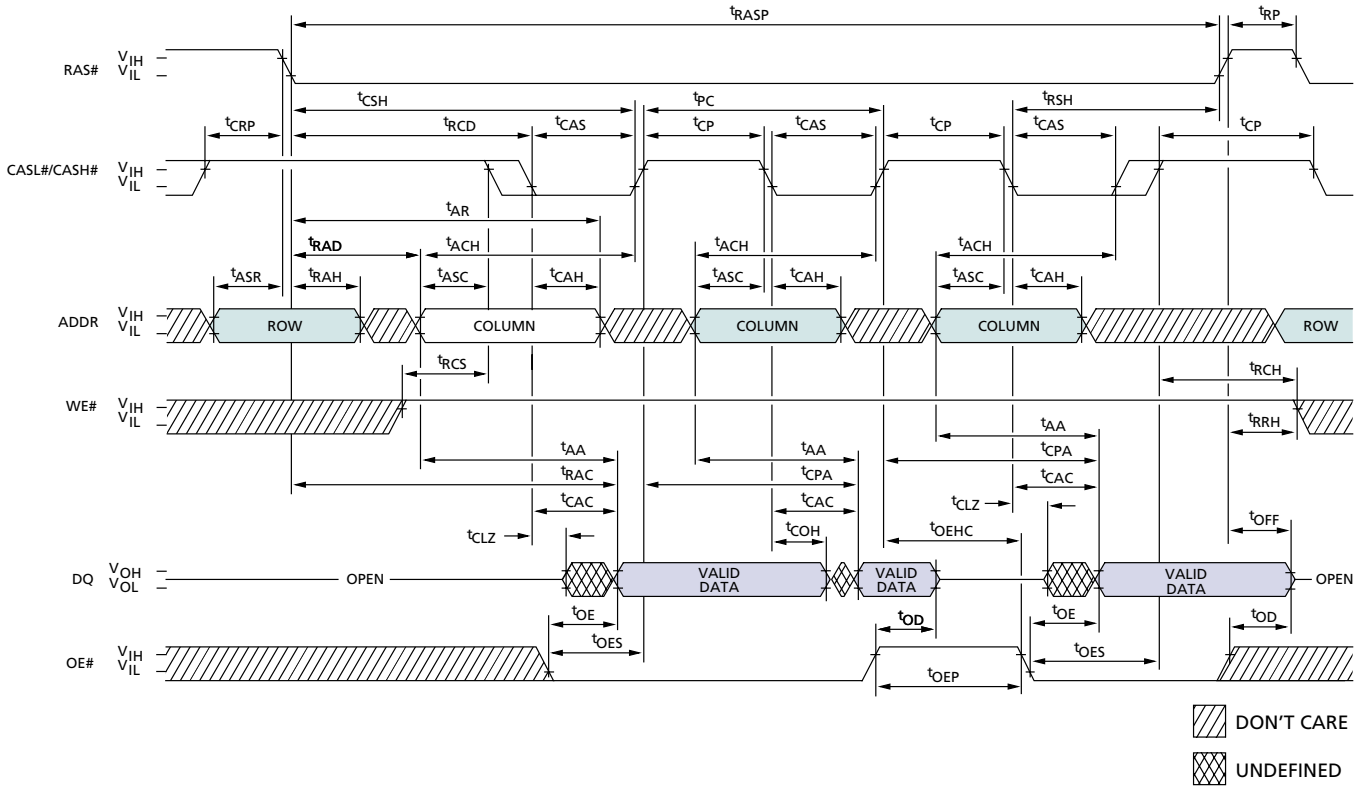


FAST PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR	40		5		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS	13	10,000	15	10,000	ns
tCLZ	3		3		ns
tCP	8		10		ns
tCPA		30		35	ns
tCRP	5		5		ns
tCSH	50		60		ns
tOD	3	13	3	15	ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOE		13		15	ns
tOFF	3	13	3	15	ns
tPC	30		35		ns
tRAC		50		60	ns
tRAD	13		15		ns
tRAH	8		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD	18		20		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRRH	0		0		ns
tRSH	13		15		ns

EDO-PAGE-MODE READ CYCLE

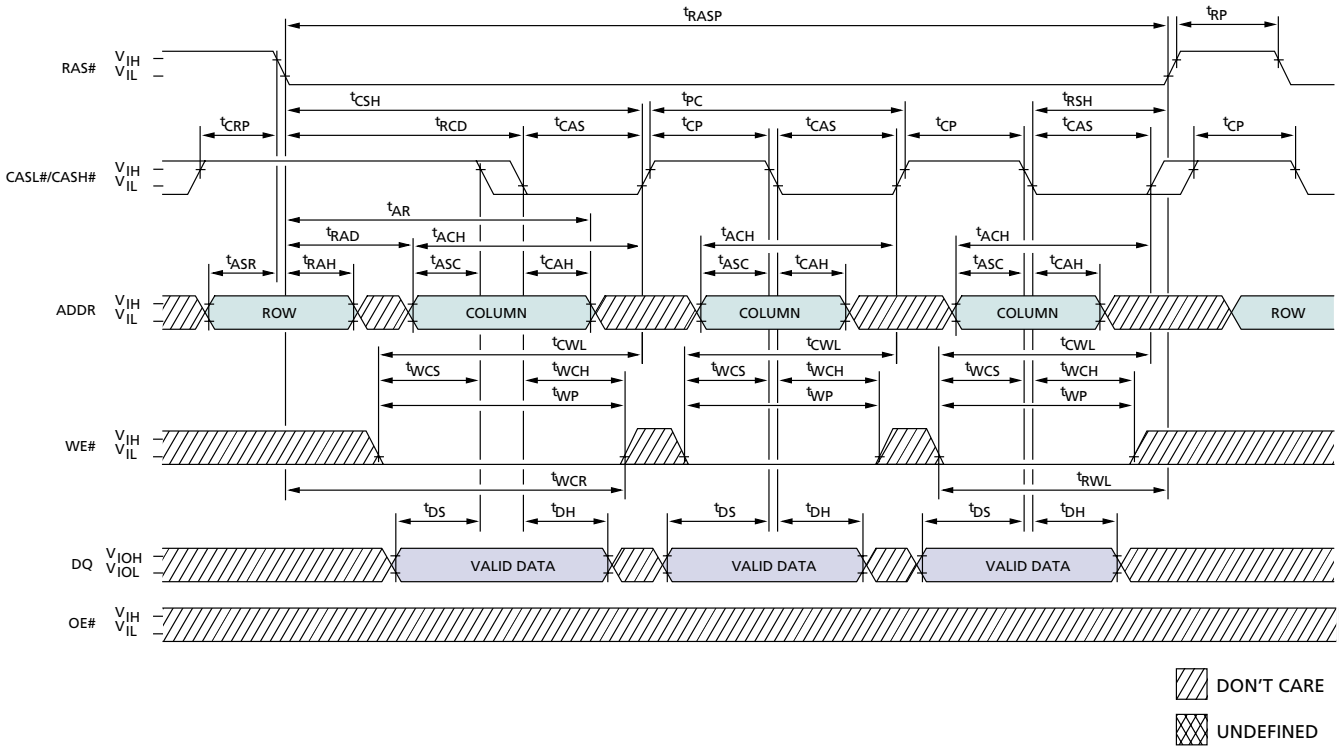


EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCLZ	0		0		ns
tCOH	3		3		ns
tCP	8		10		ns
tCPA		28		35	ns
tCRP	5		5		ns
tCSH	38		45		ns
tOD	0	12	0	15	ns
tOE		12		15	ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOEHC	5		10		ns
tOEP	5		5		ns
tOES	4		5		ns
tOFF	0	12	0	15	ns
tPC	20		25		ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRRH	0		0		ns
tRSH	13		15		ns

FAST/EDO-PAGE-MODE EARLY WRITE CYCLE[25]

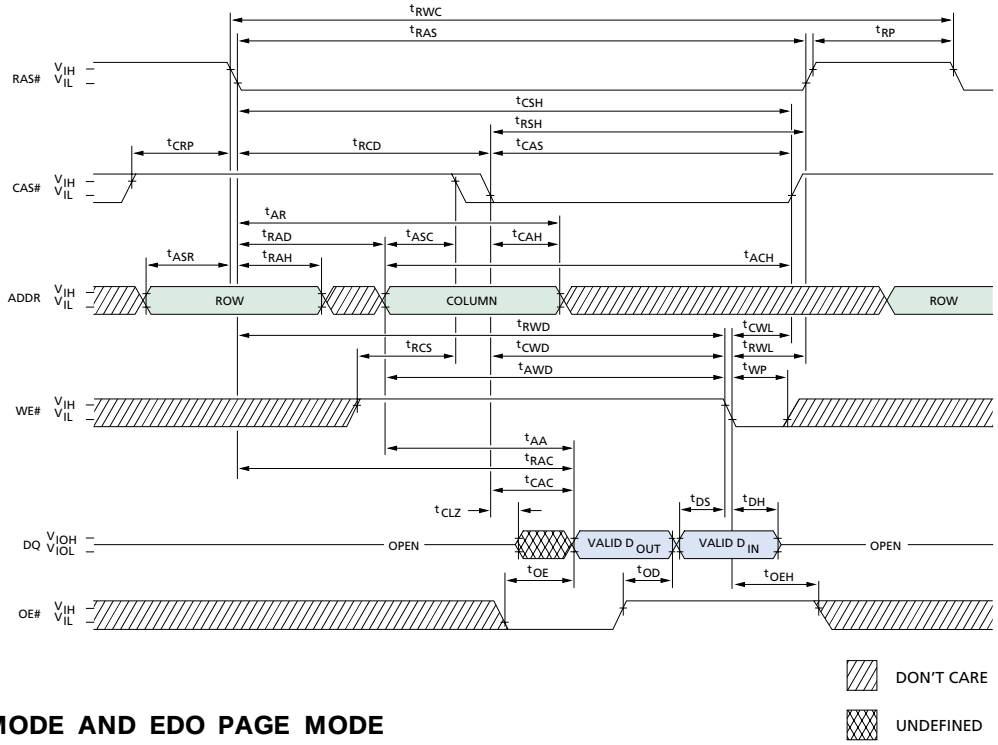


FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tACH (EDO)	12		15		ns
tAR (EDO)	38		45		ns
tAR (FPM)	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	13	10,000	15	10,000	ns
tCP	8		10		ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	50		60		ns
tCWL (EDO)	8		10		ns
tCWL (FPM)	13		15		ns
tDH	8		10		ns
tDS	0		0		ns
tPC (EDO)	20		25		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tPC (FPM)	30		35		ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	13		15		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	18		20		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWL	13		15		ns
tWCH	8		10		ns
tWCR (EDO)	38		45		ns
tWCR (FPM)	38		45		ns
tWCS	0		0		ns
tWP (EDO)	5		5		ns
tWP (FPM)	8		10		ns

READ-WRITE CYCLE [25]
(LATE WRITE and READ-MODIFY-WRITE cycles)

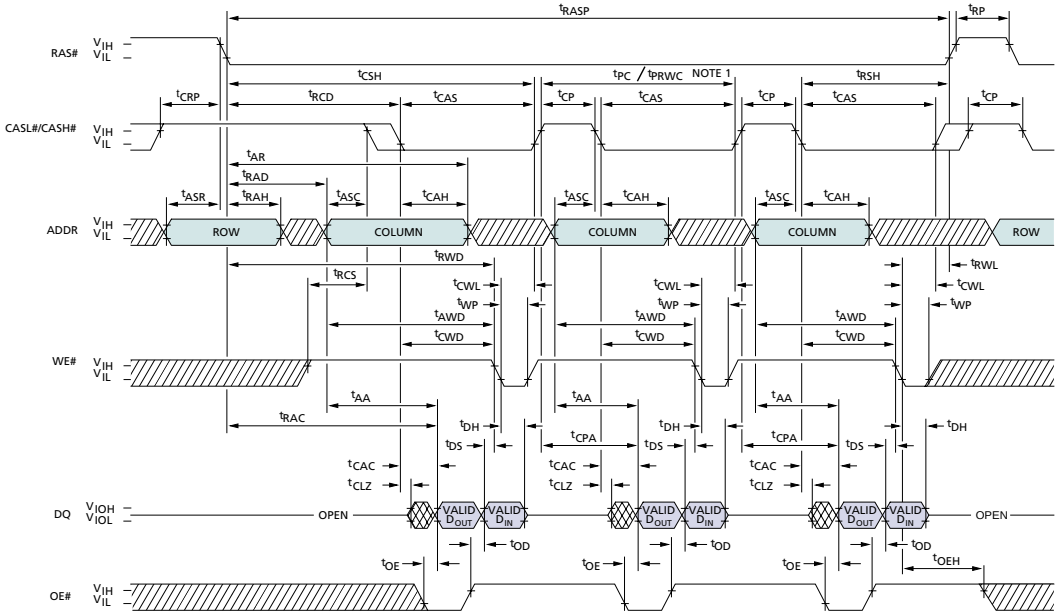


FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH (EDO)	12		15		ns
tAR (EDO)	38		45		ns
tAR (FPM)	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tAWD (EDO)	42		49		ns
tAWD (FPM)	48		55		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	13	10,000	15	10,000	ns
tCLZ (EDO)	0		0		ns
tCLZ (FPM)	3		3		ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	50		60		ns
tCWD (EDO)	28		35		ns
tCWD (FPM)	36		40		ns
tCWL (EDO)	8		10		ns
tCWL (FPM)	13		15		ns
tDH	8		10		ns
tDS	0		0		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOD (EDO)	0	12	0	15	ns
tOD (FPM)	3	13	3	15	ns
tOE (EDO)		12		15	ns
tOEH (EDO)	8		10		ns
tOEH (FPM)	13		15		ns
tRAC		50		60	ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	13		15		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRAS	50	10,000	60	10,000	ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	18		20		ns
tRCS	0		0		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWC (EDO)	116		140		ns
tRWC (FPM)	131		155		ns
tRWD (EDO)	67		79		ns
tRWD (FPM)	73		85		ns
tRWL	13		15		ns
tWP (EDO)	5		5		ns
tWP (FPM)	8		10		ns

FAST/EDO-PAGE-MODE READ-WRITE CYCLE[25]
(LATE WRITE and READ-MODIFY-WRITE cycles)



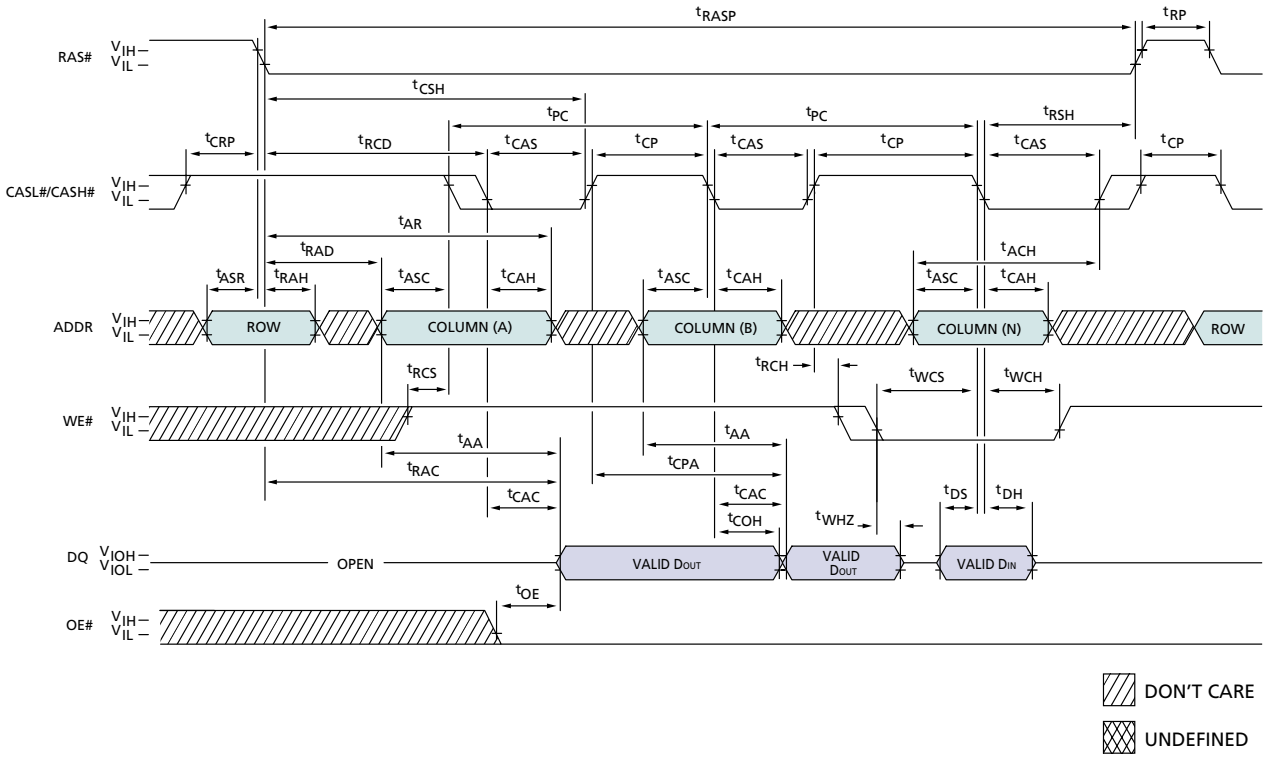
FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR (EDO)	38		45		ns
tAR (FPM)	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tAWD (EDO)	42		49		ns
tAWD (FPM)	48		55		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	13	10,000	15	10,000	ns
tCLZ (EDO)	0		0		ns
tCLZ (FPM)	3		3		ns
tCP	8		10		ns
tCPA (EDO)		28		35	ns
tCPA (FPM)		30		35	ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	50		60		ns
tCWD (EDO)	28		35		ns
tCWD (FPM)	36		40		ns
tCWL (EDO)	8		10		ns
tCWL (FPM)	13		15		ns
tDH	8		10		ns
tDS	0		0		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOD (EDO)	0	12	0	15	ns
tOD (FPM)	3	13	3	15	ns
tOE (EDO)		12		15	ns
tOE (FPM)		13		15	ns
tOEH (EDO)	8		10		ns
tOEH (FPM)	13		15		ns
tPC (EDO)	20		25		ns
tPC (FPM)	30		35		ns
tPRWC (EDO)	47		56		ns
tPRWC (FPM)	76		85		ns
tRAC		50		60	ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	13		15		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	18		20		ns
tRCS	0		0		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWD (EDO)	67		79		ns
tRWD (FPM)	73		85		ns
tRWL	13		15		ns
tWP (EDO)	5		5		ns
tWP (FPM)	8		10		ns

NOTE: 1. tPC is for LATE WRITE cycles only.

EDO-PAGE-MODE READ EARLY WRITE CYCLE
(Pseudo READ-MODIFY-WRITE)

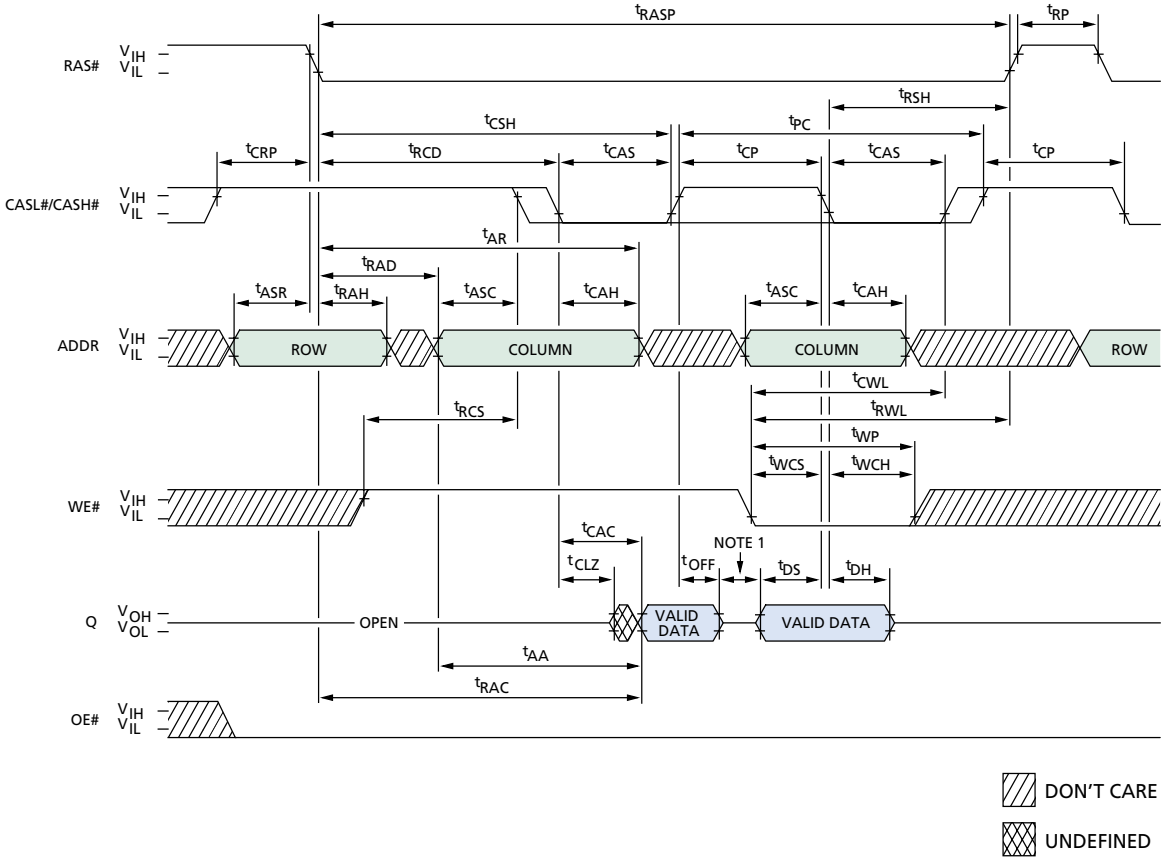


EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCOH	3		3		ns
tCP	8		10		ns
tCPA		28		35	ns
tCRP	5		5		ns
tCSH	38		45		ns
tDH	8		10		ns
tDS	0		0		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOE		12		15	ns
tPC	20		25		ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRSH	13		15		ns
tWCH	8		10		ns
tWCS	0		0		ns
tWHZ	0	12	0	15	ns

FAST-PAGE-MODE READ EARLY WRITE CYCLE
(Pseudo READ-MODIFY-WRITE)



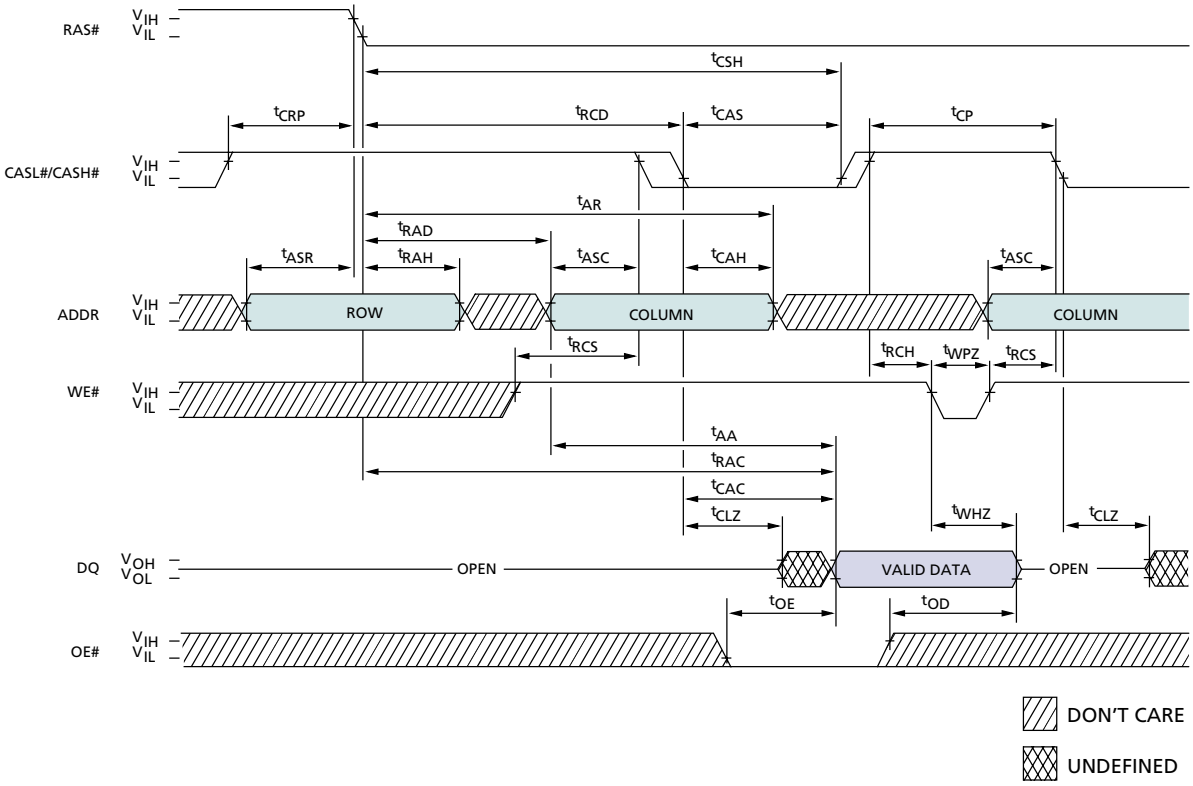
FAST PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS	13	10,000	15	10,000	ns
tCLZ	3		3		ns
tCP	8		10		ns
tCRP	5		5		ns
tCSH	50		60		ns
tCWL	13		15		ns
tDH	8		10		ns
tDS	0		0		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOFF	3	13	3	15	ns
tPC	30		35		ns
tRAC		50		60	ns
tRAD	13		15		ns
tRAH	8		10		ns
tRASP	50	10,000	60	125,000	ns
tRCD	18		20		ns
tRCS	0		0		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWL	13		15		ns
tWCH	8		10		ns
tWCS	0		0		ns
tWP	8		10		ns

NOTE: 1. Do not drive data prior to tristate.

EDO READ CYCLE
(with WE#-controlled disable)

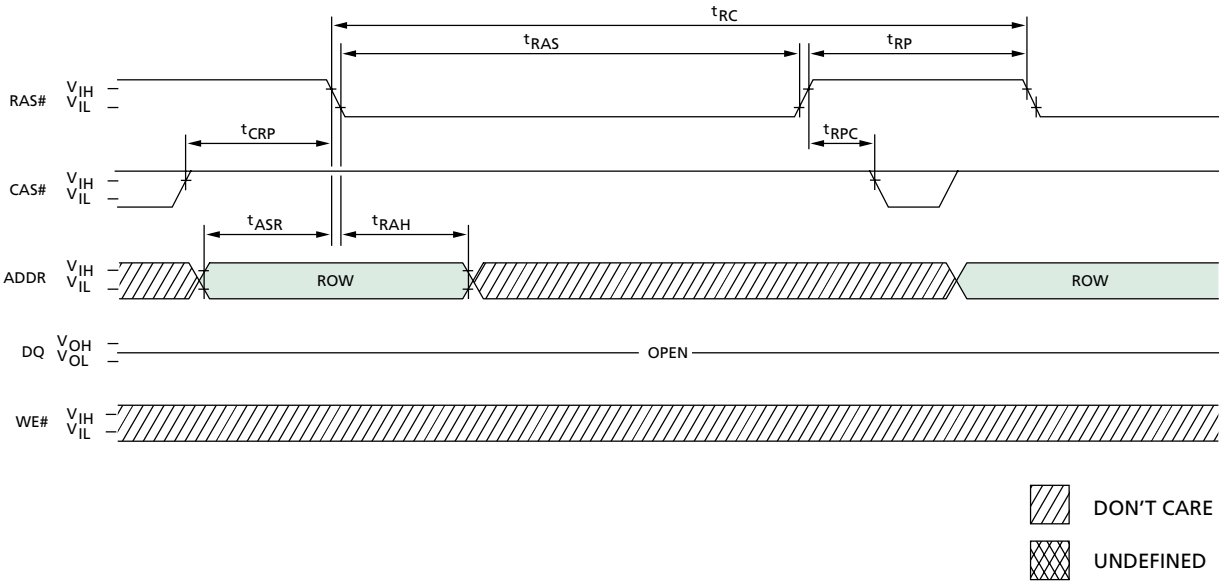


EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCLZ	0		0		ns
tCP	8		10		ns
tCRP	5		5		ns
tCSH	38		45		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOD	0	12	0	15	ns
tOE		12		15	ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tWHZ	0	12	0	15	ns
tWPZ	10		10		ns

RAS#-ONLY REFRESH CYCLE [25]

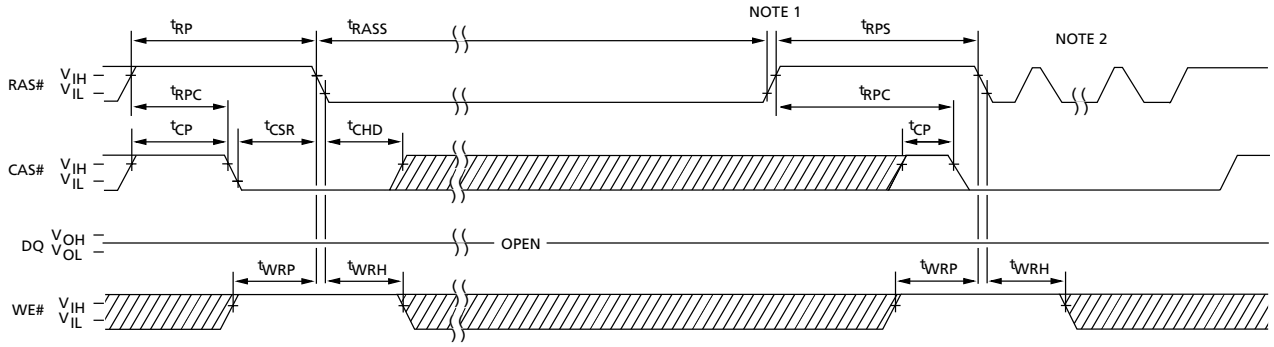


FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

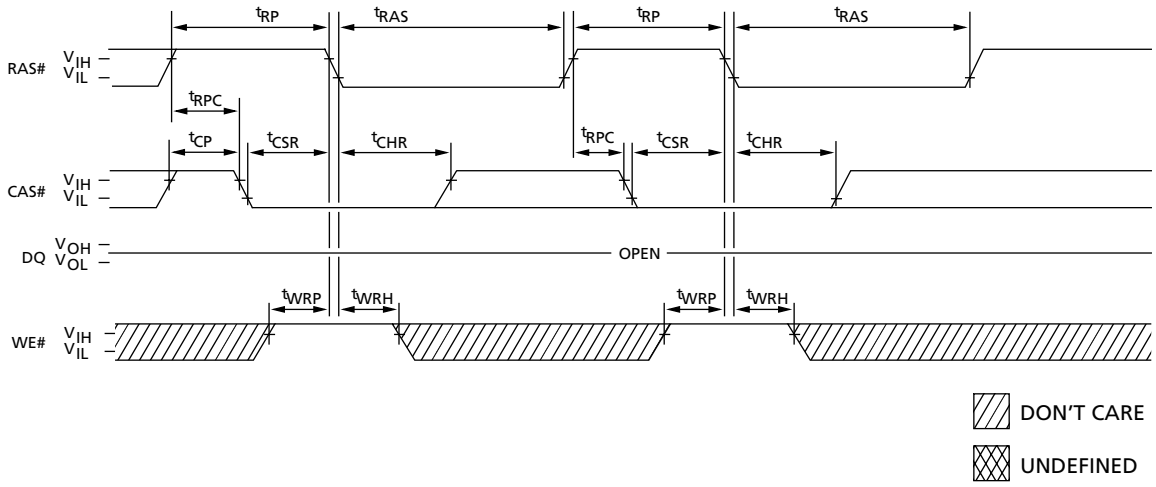
SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tASR	0		0		ns
tCRP	5		5		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRAS	50	10,000	60	10,000	ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tRC (FPM)	90		110		ns
tRC (EDO)	84		104		ns
tRP	30		40		ns
tRPC (FPM)	0		0		ns
tRPC (EDO)	5		5		ns

SELF REFRESH CYCLE
(Addresses and OE# = DON'T CARE)



CBR REFRESH CYCLE [25]
(Addresses = DON'T CARE)



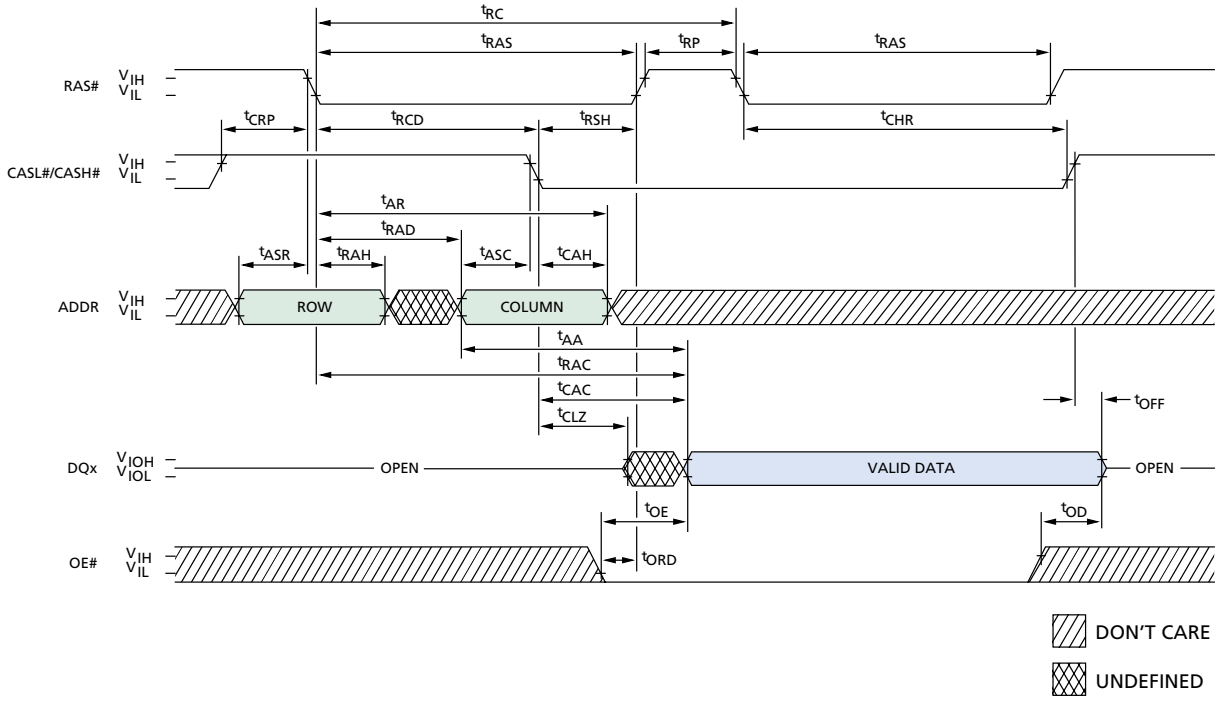
FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tCHD	15		15		ns
tCHR (FPM)	15		15		ns
tCHR (EDO)	8		10		ns
tCP	8		10		ns
tCSR	5		5		ns
tRAS	50	10,000	60	10,000	ns
tRASS	100		100		µs
tRP	30		40		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tRPC (FPM)	0		0		ns
tRPC (EDO)	5		5		ns
tRPS	90		105		ns
tWRH (EDO)	8		10		ns
tWRP (EDO)	8		10		ns
tWRN (FPM)	10		10		ns
tWRP (FPM)	10		10		ns

NOTE: 1. Once tRASS (MIN) is met and RAS# remains LOW, the DRAM will enter self refresh mode.
2. Once tRPS is satisfied, a complete burst of all rows should be executed.

HIDDEN REFRESH CYCLE [20, 25]
(WE# = HIGH)

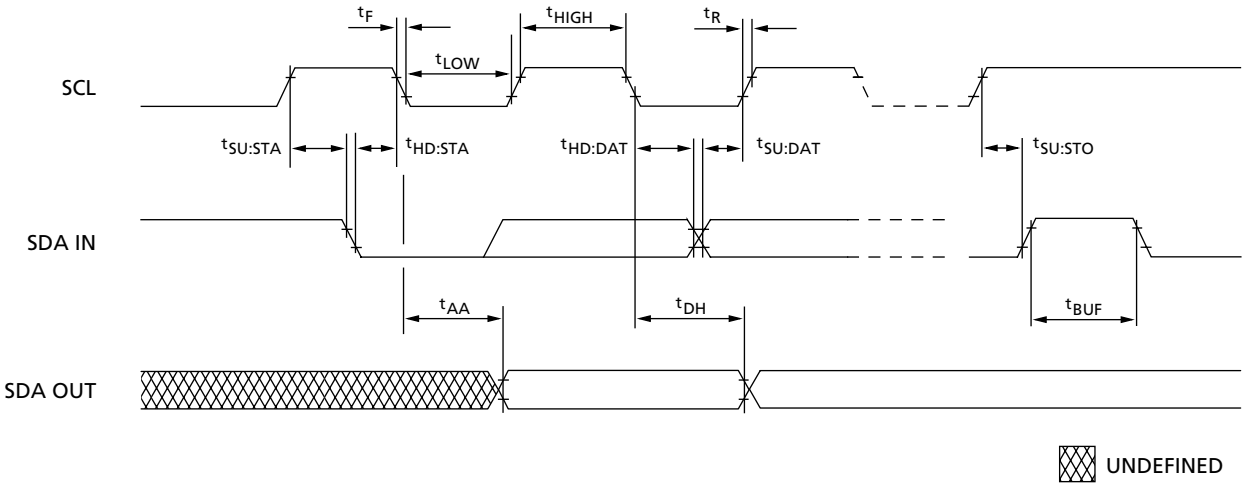


FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR (EDO)	38		45		ns
tAR (FPM)	40		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13		15	ns
tCAH	8		10		ns
tCHR (FPM)	15		15		ns
tCHR (EDO)	8		10		ns
tCLZ (FPM)	3		3		ns
tCLZ (EDO)	0		0		ns
tCRP	5		5		ns
tOD (FPM)	3	13	3	15	ns
tOD (EDO)	0	12	0	15	ns
tOE (EDO)		12		15	ns
tOE (FPM)		13		15	ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tOFF (FPM)	3	13	3	15	ns
tOFF (EDO)	0	12	0	15	ns
tORD	0		0		ns
tRAC		50		60	ns
tRAD (FPM)	13		15		ns
tRAD (EDO)	9		12		ns
tRAH (EDO)	9		10		ns
tRAH (FPM)	8		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (FPM)	90		110		ns
tRC (EDO)	84		104		ns
tRCD (FPM)	18		20		ns
tRCD (EDO)	11		14		ns
tRP	30		40		ns
tRSH	13		15		ns

SPD EEPROM



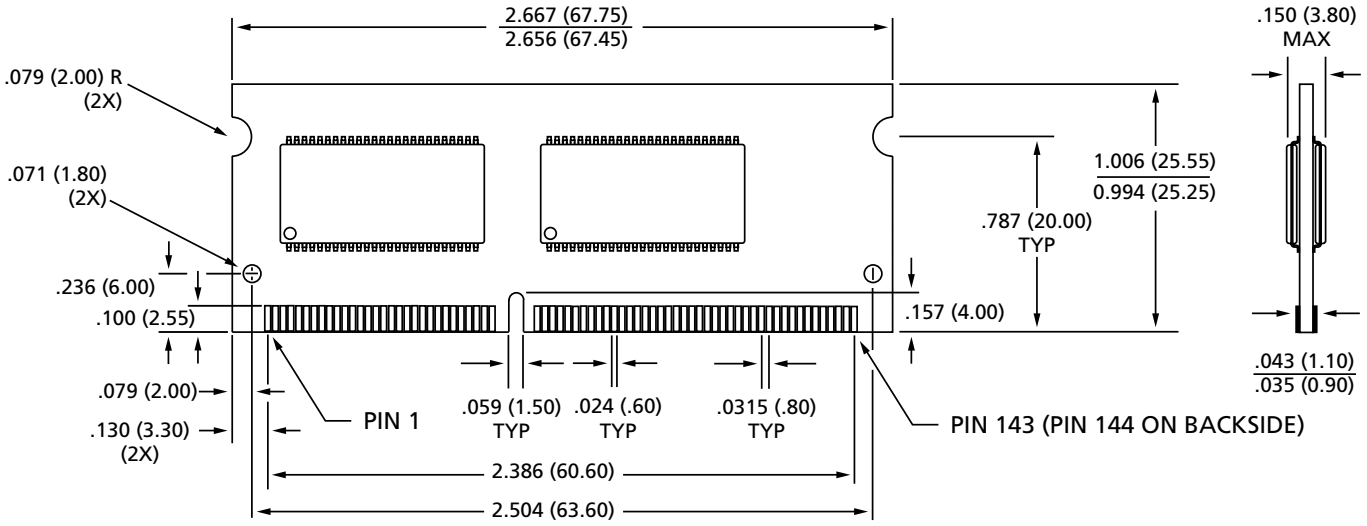
SPD EEPROM TIMING PARAMETERS

SYMBOL	MIN	MAX	UNITS
tAA	0.3	3.5	µs
tBUF	4.7		µs
tDH	300		ns
tF		300	ns
tHD:DAT	0		µs
tHD:STA	4		µs

SYMBOL	MIN	MAX	UNITS
tHIGH	4		µs
tLOW	4.7		µs
tR		1	µs
tSU:DAT	250		ns
tSU:STA	4.7		µs
tSU:STO	4.7		µs

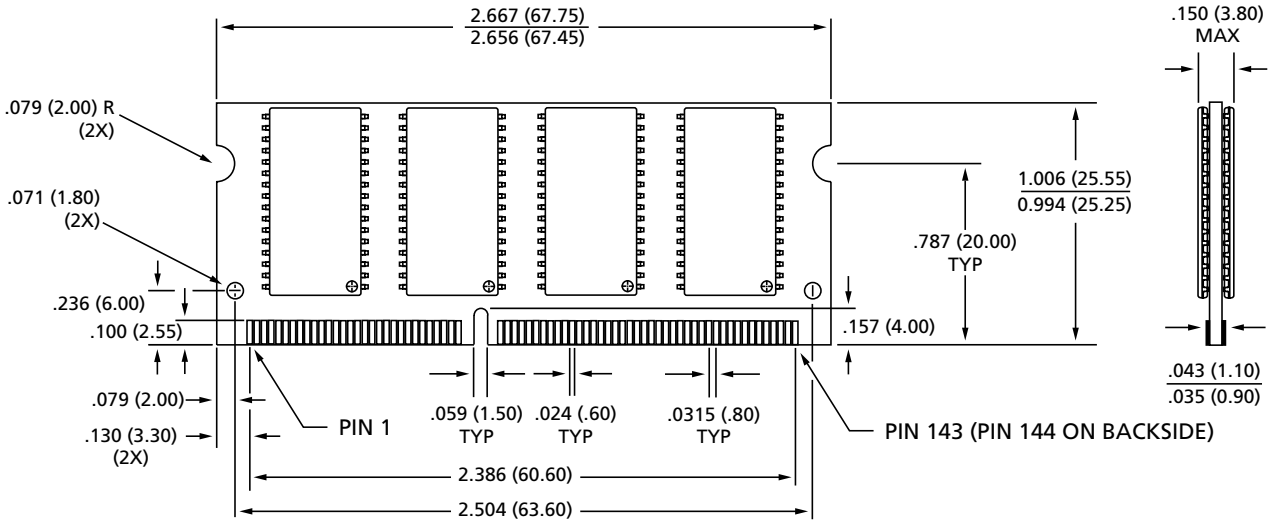
144-PIN SODIMM
DG-7 (32MB)

FRONT VIEW



144-PIN SODIMM
DG-8 (64MB)

FRONT VIEW



NOTE: All dimensions in inches (millimeters) $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.

8000 S. Federal Way, P.O. Box 6, Boise, ID 83707-0006, Tel: 208-368-3900
E-mail: prodmktg@micronsemi.com, Internet: http://www.micronsemi.com, Customer Comment Line: 800-932-4992